



Integrated Device Technology, Inc.  
2975 Stender Way, Santa Clara, CA - 95054

## PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **F0306-03**      DATE: 7/7/2003  
 Product Affected:  
 IDT723611, IDT723612, IDT723613, IDT723614, IDT723616  
 Date Effective: 10/7/2003

**MEANS OF DISTINGUISHING CHANGED DEVICES:**

- Product Mark
- Back Mark
- Date Code      "Y" Prefix
- Other

Contact: Dasharath Patel  
 Title: Quality Assurance Manager      Attachment:  Yes       No  
 Phone #: (408) 330-1488  
 Fax #: (408) 330-1450      Samples: Available now  
 E-mail: [Dasharath.Patel@idt.com](mailto:Dasharath.Patel@idt.com)

**DESCRIPTION AND PURPOSE OF CHANGE:**

- Die Technology      As a part of IDT's consolidation of wafer fab manufacturing operations, the devices listed above are transferred from FAB 2 (Salinas, CA) to FAB 4 (Hillsboro, OR). The process technology has been upgraded from CMOS 7 to CMOS 8. There is no change to data sheet specifications.
  - Wafer Fabrication Process
  - Assembly Process
  - Equipment
  - Material
  - Testing
  - Manufacturing Site      Starting 10/07/2003, customers will receive material manufactured either at FAB 2 or FAB 4. Please see below for means of distinguishing inventory.
  - Data Sheet      FAB 2 material mark      Z-Step      Date Code: Zyyww
  - Other      FAB 4 material mark      Y-Step      Date Code: Yyyww
- yy: Year      ww: Work Week

**RELIABILITY/QUALIFICATION SUMMARY:**

Please see attachment for qualification summary

**CUSTOMER ACKNOWLEDGMENT OF RECEIPT:**

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: \_\_\_\_\_  **Approval for shipments prior to effective date.**

Name/Date: \_\_\_\_\_ E-Mail Address: \_\_\_\_\_

Title: \_\_\_\_\_ Phone# /Fax# : \_\_\_\_\_

**CUSTOMER COMMENTS:** \_\_\_\_\_

**IDT ACKNOWLEDGMENT OF RECEIPT:**

RECD. BY: \_\_\_\_\_ DATE: \_\_\_\_\_



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### ATTACHMENT - PCN #: F0306-03

**PCN Type:** Process Technology Upgrade and Wafer Fabrication Site Change

**Data Sheet Change:** None

**Detail of Change:** Transfer of manufacturing site from FAB 2 (Salinas, CA) to FAB 4 (Hillsboro, OR), and process technology upgrade from CMOS 7 to CMOS 8 for the following devices:

Part Number	Old Stepping (Fab 2)	New Stepping (Fab 4)
IDT723611	Z	Y
IDT723612	Z	Y
IDT723613	Z	Y
IDT723614	Z	Y
IDT723616	Z	Y

**Note:** All speed grades and package types are affected.

#### Conversion schedule (Estimated)

Samples	Available upon request
Production Shipments	10/7/2003



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### ATTACHMENT - PCN #: F0306-03

**Qualification Plan:** QFI-03-04

**Test Vehicle:** IDT723614

Test Description/Condition	Test Methods	Required SS / # Fails	Qual Test Results SS / # Fails
Temperature Cycling (-65°C to +150°C, 500 cyc)	MIL-STD-883, Method 1010	45 / 0	45 / 0
Life Test (+125°C, 1000 hrs)	MIL-STD-883, Method 1005	116 / 0	116 / 0
Latch-Up Immunity (+ - I and V stress, + - 100 mA Trigger)	EIA/JESD 78	10 / 0	10 / 0
ESD Human Body Model	MIL-STD-883, Method 3015	3 / 0	3 / 0
ESD Charge Device Model	JESD22-C101	3 / 0	3 / 0

#### Characterization Data:

Characterization Data is available upon request.